



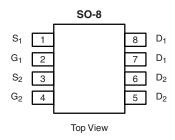
# N- and P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY				
	V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	
N-Channel	30	0.025 at V <sub>GS</sub> = 10 V	6.9	
		$0.035 \text{ at V}_{GS} = 4.5 \text{ V}$	5.8	
P-Channel	- 30	0.032 at V <sub>GS</sub> = - 10 V	- 6.1	
		0.045 at V <sub>GS</sub> = - 4.5 V	- 5.1	

#### **FEATURES**

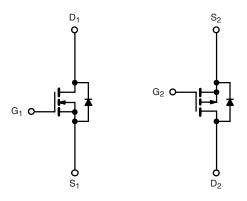
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC





Ordering Information: Si4542DY-T1-E3 (Lead (Pb)-free)

Si4542DY-T1-GE3 (Lead (Pb)-free and Halogen-free)



N-Channel MOSFET

P-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATIN</b>	<b>GS</b> T <sub>A</sub> = 25 °	°C, unless other	wise noted			
Parameter		Symbol	N-Channel	P-Channel	Unit	
Drain-Source Voltage		$V_{DS}$	30	- 30	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	± 20		
Ocation - David Ocaman (T. 150.00)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	6.9	- 6.1		
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 70 °C		5.5	- 4.9	۸	
Pulsed Drain Current		I <sub>DM</sub>	40	- 40	Α	
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	1.7	- 1.7		
Mariana Barra Birata di ang	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2.0		W	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 70 °C	' D	1.3		VV	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	N- or P-Channel	Unit		
Maximum Junction-to-Ambient <sup>a</sup>	R <sub>thJA</sub>	62.5	°C/W		

Notes:

a. Surface Mounted on FR4 board,  $t \leq 10 \ \text{s}.$ 

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SPECIFICATIONS $T_J = 25$ °	<b>SPECIFICATIONS</b> T <sub>J</sub> = 25 °C, unless otherwise noted							
Parameter	Symbol	Test Conditions		Min.	Тур.	Max.	Unit	
Static								
Gate Threshold Voltage	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	N-Ch	1.0			V	
	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = - 250 μA	P-Ch	- 1.0			V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	N-Ch			± 100	nA	
Gale-Douy Leakage			P-Ch			± 100		
	I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V	N-Ch			1		
Zero Gate Voltage Drain Current		V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V	P-Ch			- 1	μΑ	
Zero date voltage Brain Garrent	.000	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$	N-Ch			25		
		$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$	P-Ch			- 25		
On Otata Busin On 12	l <sub>lac</sub> ,	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	N-Ch	20			А	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$	P-Ch	- 20				
		$V_{GS} = 10 \text{ V}, I_D = 6.9 \text{ A}$	N-Ch		0.020	0.025		
	D	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 6.1 A	P-Ch		0.026	0.032		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 5.8 \text{ A}$	N-Ch		0.026	0.035	Ω	
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 5.1 A	P-Ch		0.036	0.045		
	_	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 6.9 A	N-Ch		25		S	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 6.1 A	P-Ch		16			
	V <sub>SD</sub>	I <sub>S</sub> = 1.7 A, V <sub>GS</sub> = 0 V	N-Ch			1.2	V	
Diode Forward Voltage <sup>a</sup>		I <sub>S</sub> = - 1.7 A, V <sub>GS</sub> = 0 V	P-Ch			- 1.2		
Dynamic <sup>b</sup>							•	
Total Gata Chargo	Qg	N-Channel	N-Ch		30	50	nC	
Total Gate Charge			P-Ch		32	50		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 6.9 \text{ A}$	N-Ch		7.5			
	ys	P-Channel	P-Ch		7.0			
Gate-Drain Charge	$Q_{gd}$	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -6.1 \text{ A}$	N-Ch		3.5			
	9-		P-Ch	0.5	5.0	0.4		
Gate Resistance	$R_{g}$		N-Ch P-Ch	0.5 2	2 4	3.4 6.8	Ω	
			N-Ch		12	20		
Turn-On Delay Time	t <sub>d(on)</sub>	N-Channel $V_{DD}$ = 15 V, $R_L$ = 10 $\Omega$	P-Ch		10	20		
			N-Ch		10	20		
Rise Time		$I_D \cong 1 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 6 \Omega$	P-Ch		10	20		
Turn-Off Delay Time	t <sub>d(off)</sub>	P-Channel	N-Ch		60	90		
		$V_{DD} = -15 \text{ V}, R_L = 10 \Omega$	P-Ch		55	80	ns	
Fall Time	t <sub>f</sub>	$I_D \cong$ - 1 A, $V_{GEN}$ = - 10 V, $R_g$ = 6 $\Omega$	N-Ch		15	30		
			P-Ch		25	40		
Source-Drain	t <sub>rr</sub>	I <sub>F</sub> = 1.7 A, dl/dt = 100 A/μs	N-Ch		50	90		
Reverse Recovery Time		I <sub>F</sub> = - 1.7 A, dl/dt = 100 A/μs	P-Ch		50	90		
Reverse Recovery Time	$Q_{rr}$	$I_F = 1.7 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}$ N-Ch			45		nC	
	11	I <sub>F</sub> = - 1.7 A, dl/dt = 100 A/μs	P-Ch		55		110	

#### Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

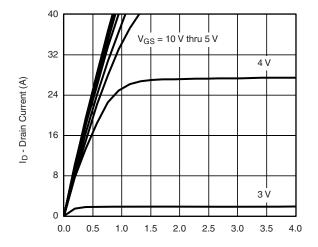
a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

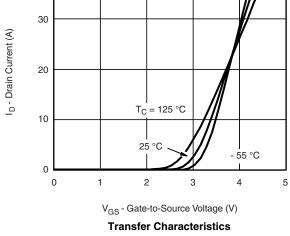




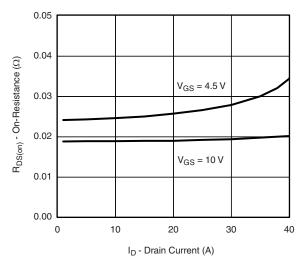
#### N-CHANNEL TYPICAL CHARACTERISTICS 25 °C unless otherwise noted



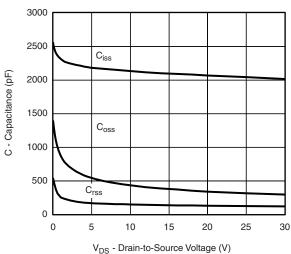
V<sub>DS</sub> - Drain-to-Source Voltage (V)



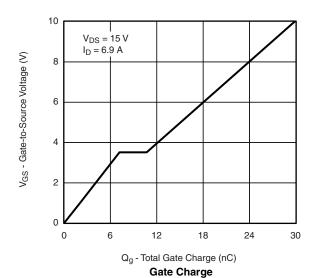
Output Characteristics

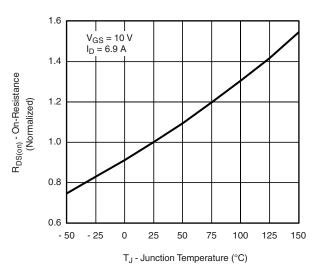


On-Resistance vs. Drain Current



Capacitance

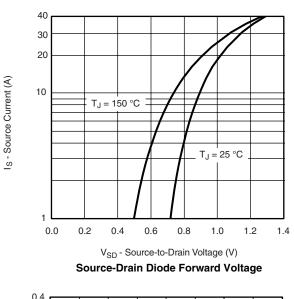


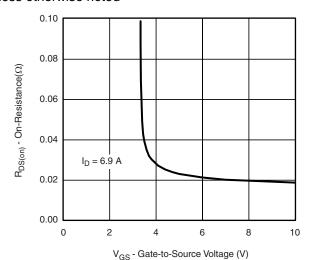


On-Resistance vs. Junction Temperature

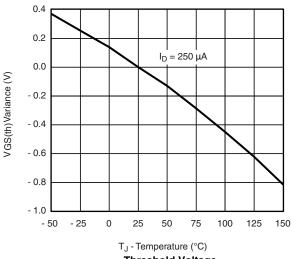
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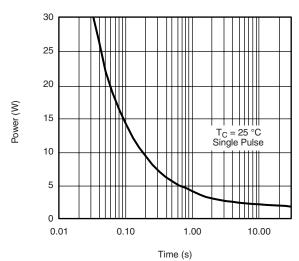
#### N-CHANNEL TYPICAL CHARACTERISTICS 25 °C unless otherwise noted





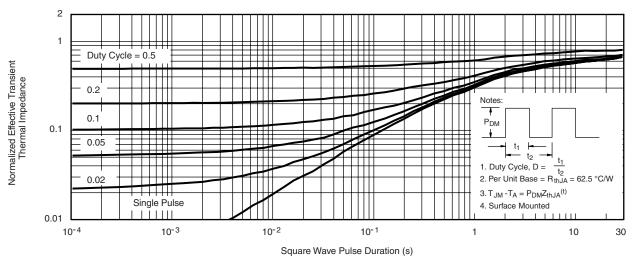






**Threshold Voltage** 

Single Pulse Power

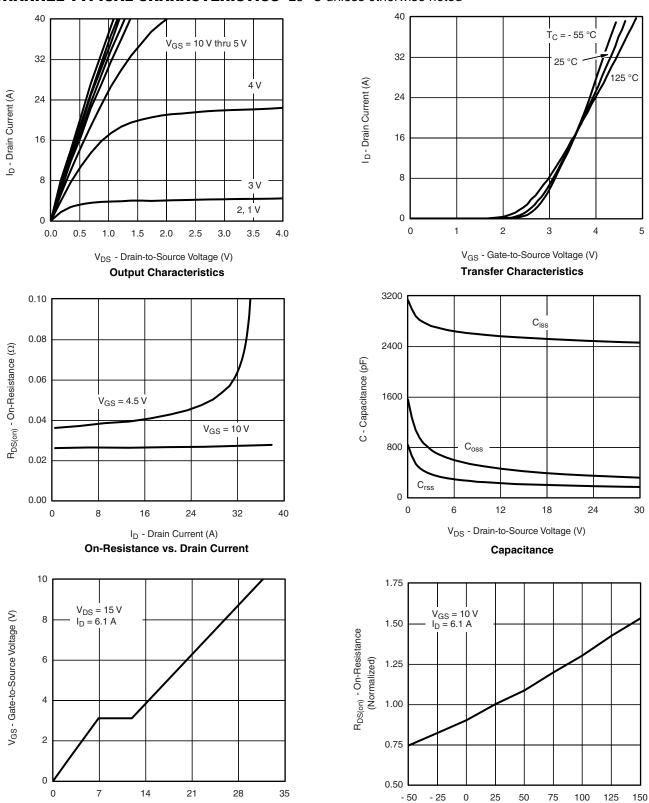


Normalized Thermal Transient Impedance, Junction-to-Ambient





#### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C unless otherwise noted



Document Number: 70666 S09-0868-Rev. G, 18-May-09

Q<sub>g</sub> - Total Gate Charge (nC)

**Gate Charge** 

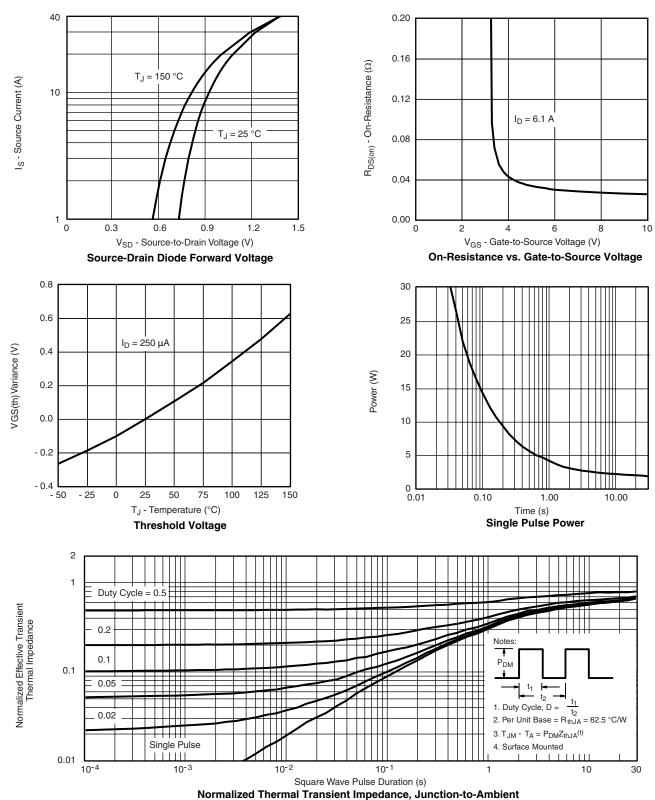
T<sub>J</sub> - Junction Temperature (°C)

On-Resistance vs. Junction Temperature

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### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C unless otherwise noted



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Document Number: 91000 www.vishay.com
Revision: 11-Mar-11 1